

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	AMENDED AND RESTATED GRANT OF PATENT SECURITY INTEREST
CONVEYING PARTY DATA	
Name	Execution Date
ALGOTOCHIP CORPORATION	11/07/2013
RECEIVING PARTY DATA	
Name:	NITTO DENKO CORPORATION
Street Address:	1-1-2, SHIMOHOZUMI
City:	IBARAKI OSAKA
State/Country:	JAPAN
Postal Code:	567-8680
PROPERTY NUMBERS Total: 17	
Property Type	Number
Patent Number:	8225247
Patent Number:	8370784
Patent Number:	8484588
Patent Number:	8185862
Patent Number:	8276107
Patent Number:	8423929
Patent Number:	8418118
Patent Number:	8336017
Patent Number:	8561005
Patent Number:	8516416
Application Number:	12835628
Application Number:	13008901
Application Number:	13452893
Application Number:	13626878
Application Number:	13672822

Application Number:	13782670
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Application Number:	13782927
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CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:

092850/9

NAME OF SUBMITTER:

ELAINE D. ZIFF

Signature:

/eziff/

Date:

11/18/2013

Total Attachments: 7

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AMENDED AND RESTATED GRANT OF PATENT SECURITY INTEREST

This **AMENDED AND RESTATED GRANT OF PATENT SECURITY INTEREST**, dated as of November 7, 2013 ("**Grant**") is by **ALGOTOCHIP CORPORATION**, a Delaware corporation located at 530 Lakeside Drive, Suite 260, Sunnyvale, California 94085 U.S.A. ("**Borrower**") in favor of **NITTO DENKO CORPORATION**, a corporation organized under the law of Japan located at 1-1-2, Shimohozumi, Ibaraki Osaka, 567-8680, Japan ("**Secured Party**").

WHEREAS, Borrower owns and will in the future acquire various intangible assets, including the Patent Collateral (as defined below); and

WHEREAS, Borrower has entered into a Loan Agreement dated as of August 28, 2012 (said Loan Agreement, as it may heretofore have been and as it may hereafter be further amended, restated, supplemented or otherwise modified from time to time, being the "**Initial Loan Agreement**") with Secured Party as Lender pursuant to which, Secured Party has made certain commitments, subject to the terms and conditions set forth in the Initial Loan Agreement, to extend a loan to Borrower; and

WHEREAS, Borrower has entered into a Loan Agreement dated as of November 7, 2013 (said Loan Agreement, as it may heretofore have been and as it may hereafter be further amended, restated, supplemented or otherwise modified from time to time, being the "**Second Loan Agreement**") with Secured Party as Lender pursuant to which, Secured Party has made certain commitments, subject to the terms and conditions set forth in the Second Loan Agreement, to extend a loan to Borrower; and

WHEREAS, Borrower has entered into a Security Agreement dated as of August 31, 2012 (said Security Agreement, being the "**Existing Security Agreement**"), by and between Borrower and Secured Party, pursuant to which Borrower has created in favor of Secured Party a security interest in, and Secured Party has become a secured creditor with respect to, the Patent Collateral; and

WHEREAS, Borrower has amended and restated the Existing Security Agreement as of November 7, 2013 (said Security Agreement, as it may heretofore have been and as it may hereafter be further amended, restated, supplemented or otherwise modified from time to time, being the "**Security Agreement**"), by and between Borrower and Secured Party, pursuant to which Borrower has created in favor of Secured Party a further security interest in, and Secured Party has become a further secured creditor with respect to, the Patent Collateral; and

WHEREAS, in consideration of the foregoing, the parties desire to amend and restate the existing Grant of Patent Security Interest dated as of August 31, 2012, by and among Algotochip Corporation and Nitto Denko Corporation (the "**Existing Patent Security Agreement**"), in its entirety as set forth herein.

Grant of Patent Security Interest
to Security Agreement

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which are hereby acknowledged, to evidence further the security interest granted by Borrower to Secured Party pursuant to the Security Agreement (i) the Existing Patent Security Agreement is amended and restated in its entirety as set forth herein and (ii) Borrower hereby (A) confirms that, pursuant to the Existing Patent Security Agreement, such Borrower granted to Secured Party, a continuing security interest in any and all right, title and interest of such Borrower in and to the Patent Collateral (as defined below), (B) ratifies, reaffirms and restates such grant of continuing security interest in any and all right, title and interest of such Borrower in and to the Patent Collateral, and (C) furthermore grants to Secured Party a security interest in, all of Borrower's right, title and interest in and to the following, in each case whether now or hereafter existing and whether now owned or hereafter acquired, or in which Borrower now has or hereafter acquires an interest and wherever the same may be located (the "**Patent Collateral**");

(i) all patents and patent applications and rights and interests in patents and patent applications under any domestic or foreign law that are presently, or in the future may be, owned or held by Borrower in whole or in part (including, without limitation, the patents and patent applications set forth on Schedule A annexed hereto, as the same may be amended pursuant hereto from time to time), and all re-issues, divisions, continuations, renewals, extensions and continuations-in-part thereof;

(ii) all rights (but not obligations) to sue and recover for past, present and future infringements or other violations of rights in the Patents; and

(iii) all "proceeds" as defined in the UCC including, without limitation, all proceeds, products, rents and profits of or from any and all of the foregoing Patent Collateral and, to the extent not otherwise included, all payments under insurance (whether or not Secured Party is the loss payee thereof), or any indemnity, warranty or guaranty, payable by reason of loss or damage to or otherwise with respect to any of the foregoing Patent Collateral, including, but not limited to, whatever is receivable or received when Patent Collateral or proceeds are sold, licensed, leased exchanged, collected or otherwise disposed of, whether such disposition is voluntary or involuntary.

Borrower does hereby further acknowledge and affirm that the rights and remedies of Secured Party with respect to the security interest in the Patent Collateral granted hereby are more fully set forth in the Security Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein. In the event of an irreconcilable conflict between the Security Agreement and this Grant, the Security Agreement shall control.

The term of this Grant is co-extensive with the term of the Security Agreement.

This Grant and the rights and obligations of the parties hereunder shall be governed by, and shall be construed and enforced in accordance with, the internal laws of the state of New York (including, without limitation, section 5-1401 of the general obligations law of the state of New York), without regard to conflicts of laws principles.

Grant of Patent Security Interest
to Security Agreement

This Grant may be executed in one or more counterparts and by different parties hereto in separate counterparts, each of which when so executed and delivered shall be deemed an original, but all such counterparts together shall constitute but one and the same instrument; signature pages may be detached from multiple separate counterparts and attached to a single counterpart so that all signature pages are physically attached to the same document.

Borrower hereby consents to the recording of this Grant in the relevant Intellectual Property filing offices.

[Signature pages to follow]

Grant of Patent Security Interest
to Security Agreement

PATENT
REEL: 031666 FRAME: 0271

IN WITNESS WHEREOF, Borrower and Secured Party have caused this GRANT OF PATENT SECURITY INTEREST to be duly executed and delivered by its officers thereunto duly authorized as of the 6th day of November, 2013.

ALGOTOCHI CORPORATION

By: [Signature]
Name: Tak Shigihara
Title: President and CEO

STATE OF CALIFORNIA)
) ss.
COUNTY OF SANTA CLARA)

On 6 NOV, 2013, before me, S. Kaur, a Notary Public, personally appeared Takashi Shigihara, who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



(SEAL)

[Signature]
Signature of Notary Public

[Signature Page to Grant of Patent Security Interest]

NITTO DENKO CORPORATION

By: _____

Name: Toshihiko OMOTE

Title: Board Member

Executive Vice President & CTO

Director Corporate Technology Sector

STATE OF CALIFORNIA)

) ss.

COUNTY OF SANTA CLARA)

On Nov 7, 2013, before me, S. KAUR, a Notary
Public, personally appeared Toshihiko Omote —

_____, who
proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are
subscribed to the within instrument and acknowledged to me that he/she/they executed the same
in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument
the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the
foregoing paragraph is true and correct.

WITNESS my hand and official seal.



(SEAL)

S. Kaur
Signature of Notary Public

[Signature Page to Grant of Patent Security Interest]

**SCHEDULE A
TO
GRANT OF PATENT SECURITY INTEREST**

Jurisdiction	Title	Patent No. (App. No.)	Issue Date (App. Date)	Record Owner	Status/ Comments
USA	1. Automatic optimal integrated circuit generator for algorithms and specification (Conceptual)	8225247 (12/835,603)	7/17/2012 (07/13/2010)	Algotochip Corporation	Issued
USA	2. Automatic optimal integrated circuit generator from algorithms and specification (detailed)	8370784 (12/835,621)	2/5/2013 (7/13/2010)	Algotochip Corporation	Issued
USA	3. Application driven power gating	(12/835,628)	(7/13/2008)	Algotochip Corporation	Published
USA	4. System, architecture and micro-architecture (sama) representation of an integrated circuit	8484588 (12/835,631)	7/9/2013 (7/13/2010)	Algotochip Corporation	Issued
USA	5. Architectural level power-aware optimization and risk mitigation cross-referenced applications	8185862 (12/835,640)	5/22/2012 (7/13/2010)	Algotochip Corporation	Issued
USA	6. Integrated data model based framework for driving design convergence from architecture optimization to physical design closure	8276107 (12/906,785)	9/25/2012 (10/18/2010)	Algotochip Corporation	Issued
USA	7. Intelligent architecture creator	8423929 (12/906,857)	4/16/2013 (10/18/2010)	Algotochip Corporation	Issued
USA	8. Architecture guided optimal system precision definition algorithm for custom integrated circuit	8418118 (12/906,804)	4/9/2013 (10/18/2010)	Algotochip Corporation	Published
USA	9. Tool generator	(13/008,901)	(1/19/2011)	Algotochip Corporation	Published
USA	10. Architecture optimizer	8336017 (12/008,900)	12/18/2012 (1/19/2011)	Algotochip Corporation	Issued
USA	11. Programmatic auto-convergent method for physical design floorplan aware re-targetable tool suite generation (compiler-in-the-loop) for simultaneous instruction level (software) power optimization and architecture level performance optimization for ASIP design	8561005 (13/452,891)	10/15/2013 (4/22/2012)	Algotochip Corporation	Issued
USA	12. Programmatic auto-convergent method for "physical layout power hot-spot" risk aware ASIP architecture customization for performance optimization	(13/452,893)	(4/22/2012)	Owned by Inventors	Published
USA	13. Integrated data model based framework for driving design convergence from architecture optimization to physical design closure	8516416 (13603421)	8/20/2013 (9/5/2012)	Algotochip Corporation	Issued

Jurisdiction	Title	Patent No. (App. No.)	Issue Date (App. Date)	Record Owner	Status/ Comments
USA	14. Automatic optimal integrated circuit generator from algorithms and specification	(13626878)	(9/25/2012)	Algotochip Corporation	Published
USA	15. Automatic optimal integrated circuit generator from algorithms and specification	(13672822)	(11/9/2012)	Algotochip Corporation	Published
USA	REDACTED	(13782670)	(3/1/2013)	N/A	Unpublished
USA		(13782927)	(3/1/2013)	N/A	Unpublished